

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT8401782

|                                                                                                                                                                                                 |                               |                       |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------------------------|-----------------------|
| <b>SUBMISSION TYPE:</b>                                                                                                                                                                         | NEW ASSIGNMENT                |                       |
| <b>NATURE OF CONVEYANCE:</b>                                                                                                                                                                    | ASSIGNMENT                    |                       |
| <b>CONVEYING PARTY DATA</b>                                                                                                                                                                     |                               |                       |
|                                                                                                                                                                                                 | <b>Name</b>                   | <b>Execution Date</b> |
|                                                                                                                                                                                                 | HENKEL CORPORATION            | 11/06/2014            |
| <b>RECEIVING PARTY DATA</b>                                                                                                                                                                     |                               |                       |
| <b>Name:</b>                                                                                                                                                                                    | HENKEL US IP LLC              |                       |
| <b>Street Address:</b>                                                                                                                                                                          | ONE HENKEL WAY                |                       |
| <b>City:</b>                                                                                                                                                                                    | ROCKY HILL                    |                       |
| <b>State/Country:</b>                                                                                                                                                                           | CONNECTICUT                   |                       |
| <b>Postal Code:</b>                                                                                                                                                                             | 06067                         |                       |
| <b>PROPERTY NUMBERS Total: 1</b>                                                                                                                                                                |                               |                       |
| <b>Property Type</b>                                                                                                                                                                            | <b>Number</b>                 |                       |
| <b>Application Number:</b>                                                                                                                                                                      | 17823294                      |                       |
| <b>CORRESPONDENCE DATA</b>                                                                                                                                                                      |                               |                       |
| <b>Fax Number:</b>                                                                                                                                                                              |                               |                       |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |                               |                       |
| <b>Phone:</b>                                                                                                                                                                                   | 9085301379                    |                       |
| <b>Email:</b>                                                                                                                                                                                   | rhpattentmail@henkel.com      |                       |
| <b>Correspondent Name:</b>                                                                                                                                                                      | HENKEL CORPORATION            |                       |
| <b>Address Line 1:</b>                                                                                                                                                                          | ONE HENKEL WAY                |                       |
| <b>Address Line 4:</b>                                                                                                                                                                          | ROCKY HILL, CONNECTICUT 06067 |                       |
| <b>ATTORNEY DOCKET NUMBER:</b>                                                                                                                                                                  | 2012P31606US05                |                       |
| <b>NAME OF SUBMITTER:</b>                                                                                                                                                                       | CSABA ATTILA SZAKOLCZAI       |                       |
| <b>SIGNATURE:</b>                                                                                                                                                                               | /Csaba Attila Szakolczai/     |                       |
| <b>DATE SIGNED:</b>                                                                                                                                                                             | 01/25/2024                    |                       |
| <b>Total Attachments: 33</b>                                                                                                                                                                    |                               |                       |
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## CONFIRMATORY ASSIGNMENT – UNITED STATES OF AMERICA/I

WHEREAS,

**HENKEL CORPORATION** of One Henkel Way, Rocky Hill, CT, 06067, United States of America;  
(the "Assignor"),

was the owner of inventions in the United States of America set forth and described in Schedule I  
attached hereto and forming a part of this document (the "Inventions")

AND WHEREAS,

**HENKEL US IP LLC** of One Henkel Way, Rocky Hill, CT 06067, United States of America; (the  
"Assignee"),

had as of October 1, 2013 (the "Effective Date") acquired the entire right, title, interest, property and  
benefit in and for the United States of America, in and to the Inventions held by the Assignor;

NOW THEREFORE, for good and valuable consideration already provided, the receipt and sufficiency of  
which are hereby acknowledged,

the Assignor confirms by these presents that the Assignor had, as of the Effective Date, assigned,  
transferred and set over to the Assignee, and to the Assignee's successors, assigns, nominees or other  
legal representatives, its entire right, title, interest, property and benefit including any right to sue for past  
infringements in and for the United States of America, in and to the Inventions, any and all applications  
filed therefor, including any and all corresponding applications whether in the form of divisions,  
continuations, re-examinations, re-issues and extensions thereof, any and all patents that may issue, be  
granted or result therefrom for the Inventions, and any and all rights of priority resulting from the filing of  
any of the above-identified applications and any previously filed applications in respect of the Inventions  
under international conventions, treaties or otherwise, the same to be held and enjoyed as fully and  
exclusively as the same would have been held and enjoyed by the Assignor had this assignment not been  
made;

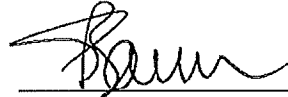
the Assignor agrees to do all lawful acts and to execute and deliver, without further consideration,  
all further documents as may reasonably be required by the Assignee, or by its successors, assigns,  
nominees, or other legal representatives, to obtain said patents in the United States of America for the  
Inventions and vests or secures the same in the Assignee, and in the Assignee's successors, assigns,  
nominees or other legal representatives; and

the Assignor grants to said Assignee, its successors, assigns, nominees or other legal  
representatives, agents, the power to insert on this Confirmatory Assignment any further information  
which may be necessary or desirable in order to legally record this document.

THIS CONFIRMATORY ASSIGNMENT may be executed in counterparts, all of which shall be considered one and the same agreement, and is binding on the heirs, executors, successors and administrators of the Assignor.

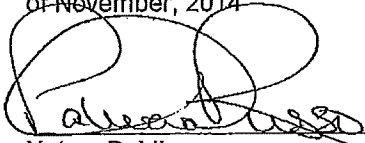
**HENKEL CORPORATION**

By



Name: Steven C. Bauman  
Title: Senior Patent Counsel

Subscribed and sworn  
before me this 6<sup>th</sup> day  
of November, 2014



Notary Public

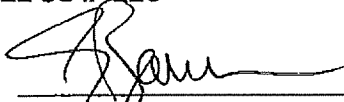
**PATRICIA D. RUSSO**  
**NOTARY PUBLIC**  
MY COMMISSION EXPIRES NOV. 30, 2014

Date:

November 6, 2014

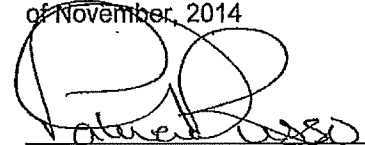
**HENKEL US IP LLC**

By



Name: Steven C. Bauman  
Title: Senior Patent Counsel

Subscribed and sworn  
before me this 6<sup>th</sup> day  
of November, 2014



Notary Public

**PATRICIA D. RUSSO**  
**NOTARY PUBLIC**  
MY COMMISSION EXPIRES NOV. 30, 2014

Date:

November 6, 2014

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Schedule I

|      | A        | B      | D  | E           | F            | G           | H             | M                                                                   |
|------|----------|--------|----|-------------|--------------|-------------|---------------|---------------------------------------------------------------------|
|      | PT026750 | N-1598 | GB | 22 Aug 1996 | 96 113 481.4 | 31 May 2000 | 0761795       | HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS                   |
| 1291 | PT026750 | N-1598 | IT | 22 Aug 1996 | 96 113 481.4 | 31 May 2000 | 0761795       | HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS                   |
| 1292 | PT026750 | N-1598 | SE | 22 Aug 1996 | 96 113 481.4 | 31 May 2000 | 0761795       | HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS                   |
| 1293 | PT026750 | N-1598 | US | 23 May 1996 | 08/652072    | 12 May 1998 | 5750605       | HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS                   |
| 1294 | PT026751 | N-1600 | CA | 02 Aug 1996 | 2182713      | 02 Jul 2002 | 2182713       | HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY |
| 1295 | PT026751 | N-1600 | DE | 06 Aug 1996 | 96112676.0   | 31 Mar 1999 | 69601905.1-08 | HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY |
| 1296 | PT026751 | N-1600 | FR | 06 Aug 1996 | 96 112 676.0 | 31 Mar 1999 | 0758009       | HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY |
| 1297 | PT026751 | N-1600 | IT | 06 Aug 1996 | 96 112 676.0 | 31 Mar 1999 | 0758009       | HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY |
| 1298 | PT026751 | N-1600 | SE | 06 Aug 1996 | 96 112 676.0 | 31 Mar 1999 | 0758009       | HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY |
| 1299 | PT026751 | N-1600 | US | 08 Aug 1995 | 08/512579    | 24 Sep 1996 | 5559165       | HOT MELT ADHESIVES FOR BONDING TO SENSITIVE AREAS OF THE HUMAN BODY |
| 1300 | PT026752 | N-1603 | US | 26 Aug 1997 | 08/918879    | 22 Dec 1998 | 5852117       |                                                                     |
| 1301 | PT026758 | N-1614 | US | 25 Aug 1997 | 08/918173    | 29 Jun 1999 | 5916968       | ADHESIVES RESISTANT TO SKIN-PENETRATING ENHANCERS                   |
| 1302 |          |        |    |             |              |             |               |                                                                     |

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Schedule I

|      | A        | B      | D  | E           | F            | G           | H             | M                                                                                |
|------|----------|--------|----|-------------|--------------|-------------|---------------|----------------------------------------------------------------------------------|
| 1303 | PT026759 | N-1617 | US | 12 Apr 1996 | 08/631390    | 11 Nov 1997 | 5685758       | HOT MELT ADHESIVE COMPOSITIONS WITH IMPROVED WICKING PROPERTIES                  |
| 1304 | PT026760 | N-1618 | US | 12 Apr 1996 | 08/631388    | 03 Mar 1998 | 5723636       | METHYLTRIOXORHENIUM-UREA HYDROGEN PEROXIDE EPOXIDATION OF OLEFINS                |
| 1305 | PT026763 | N-1623 | US | 09 Apr 1996 | 08/629851    | 03 Mar 1998 | 5723222       | CHEMICALLY DERIVATIZED MALTODEXTRINS                                             |
| 1306 | PT026764 | N-1625 | US | 06 May 1996 | 08/643644    | 18 Aug 1998 | 5795397       | HIGH SOLIDS, MALTODEXTRIN-BASED ADHESIVES                                        |
| 1307 | PT026765 | N-1626 | US | 06 May 1996 | 08/643643    | 18 Nov 1997 | 5688845       | HIGH SOLIDS, MALTODEXTRIN-BASED ADHESIVES                                        |
|      | PT026765 | N-1626 | US | 30 Apr 1997 | 08/841555    | 03 Aug 1999 | 5932639       |                                                                                  |
| 1308 | PT026767 | N-1633 | US | 05 Aug 1996 | 08/693920    | 19 May 1998 | 5753468       | STABLE HIGH-VISCOSITY STARCH BASED ADHESIVE AND METHOD OF PREPARATION            |
| 1309 | PT026770 | N-1640 | US | 27 Sep 1996 | 08/722786    | 10 Feb 1998 | 5716441       | STARCH-BASED, WATER RESISTANT ADHESIVES                                          |
|      | PT026771 | N-1642 | EP | 21 Jul 1997 | 97112455.7   | 20 Jun 2001 | 0832906       | WATER RESISTANT, VISCOSITY STABLE, ALKALINE CORRUGATING ADHESIVE COMPOSITION     |
| 1311 | PT026771 | N-1642 | US | 18 Dec 1998 | 09/215821    | 03 Jul 2001 | 6255369       | WATER RESISTANT, VISCOSITY STABLE, ALKALINE CORRUGATING ADHESIVE COMPOSITION     |
| 1312 | PT026771 | N-1642 | US | 27 Feb 2001 | 09/802533    | 23 Apr 2002 | 6375775       | WATER RESISTANT, VISCOSITY STABLE, ALKALINE CORRUGATING ADHESIVE COMPOSITION     |
| 1313 | PT026775 | N-1666 | BE | 14 Oct 1997 | 97 911 739.7 | 24 Jul 2002 | 0935616       | ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURING SAME |
| 4    | PT026775 | N-1666 | CH | 14 Oct 1997 | 97 911 739.7 | 24 Jul 2002 | 0935616       | ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURING SAME |
| 15   | PT026775 | N-1666 | DE | 31 Oct 1996 | 19643959.0   |             |               | ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURING SAME |
| 16   | PT026775 | N-1666 | DE | 14 Oct 1997 | 97911739.7   | 24 Jul 2002 | 69714280.9-08 | ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURING SAME |

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Schedule I

|      | A        | B      | D  | E           | F               | G           | H               | M                                                                                                                          |
|------|----------|--------|----|-------------|-----------------|-------------|-----------------|----------------------------------------------------------------------------------------------------------------------------|
|      | PT026775 | N-1666 | TR | 14 Oct 1997 | 99/930          | 21 May 2009 | TR 1999 00930 B | ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURING SAME                                           |
| 1325 | PT026775 | N-1666 | US | 12 Sep 1997 | 08/928313       | 23 Nov 1999 | 5990229         | ADHESIVES WITH LOW LEVEL OF RESIDUAL MONOMERS AND PROCESS FOR MANUFACTURING SAME                                           |
| 1326 | PT026776 | N-1669 | JP | 15 May 1998 | 0               |             |                 | REACTIVE RADIATION- OR THERMALLY-INITIATED CATIONICALLY- CURABLE EPOXIDE MONOMERS AND COMPOSITIONS MADE FROM THOSE MONOMER |
| 1327 | PT026776 | N-1669 | US | 14 May 1998 | 09/078768       | 05 Oct 1999 | 5962547         | REACTIVE RADIATION- OR THERMALLY-INITIATED CATIONICALLY- CURABLE EPOXIDE MONOMERS AND COMPOSITIONS MADE FROM THOSE MONOMER |
| 1328 | PT026778 | N-1674 | MX | 01 Jul 1998 | 985377          | 28 Jul 2011 | 288800          | ABSORBENT ARTICLES COMPRISING A POLYETHER- CONTAINING HOT MELT ADHESIVE AND HOTMELT ADHESIVE COMPOSITIONS COMPRISING POLY  |
| 1329 | PT026778 | N-1674 | TW | 01 Jul 1998 | 87110675        |             |                 | ABSORBENT ARTICLES COMPRISING A POLYETHER- CONTAINING HOT MELT ADHESIVE AND HOTMELT ADHESIVE COMPOSITIONS COMPRISING POLY  |
| 1330 | PT026779 | N-1675 | US | 28 Jul 1997 | 08/901305       | 22 Dec 1998 | 5852080         | HOT MELT ADHESIVES WITH COMPATIBLE HYDROXYL- CONTAINING ESTER WAXES                                                        |
| 1331 | PT026782 | N-1683 | US | 26 Aug 1997 | 08/918795       | 23 Mar 1999 | 5886021         | STABLE HIGH PERFORMANCE, ONE PART ACRYLIC ADHESIVE SYSTEM □                                                                |
| 1332 | PT026784 | N-1688 | US | 02 Jun 1995 | 08/460357       |             |                 | THE SYNTHESIS OF CONDENSATION POLYMERS IN- DENSIFIED FLUIDS                                                                |
| 3    | PT026784 | N-1688 | US | 14 Feb 1997 | 08/800371       | 16 Jan 2001 | 6174956         | THE SYNTHESIS OF CONDENSATION POLYMERS IN DENSIFIED FLUIDS                                                                 |
| 4    | PT026785 | N-1690 | DE | 12 Oct 1998 | EP19980119240.4 | 15 Mar 2006 | 69833823.5-08   | FAST SETTING POLYURETHANE HOT MELT ADHESIVE                                                                                |
| 15   | PT026785 | N-1690 | JP | 14 Oct 1998 | 10-292104       |             |                 | FAST SETTING POLYURETHANE HOT MELT ADHESIVE                                                                                |
| 16   |          |        |    |             |                 |             |                 |                                                                                                                            |

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REEL: 066369 FRAME: 0885

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Schedule 1

|      | A        | B      | D  | E           | F          | G           | H          | M                                                                                        |
|------|----------|--------|----|-------------|------------|-------------|------------|------------------------------------------------------------------------------------------|
|      | PT026785 | N-1690 | US | 15 Oct 1997 | 08/951055  | 17 Aug 1999 | 5939488    | FAST SETTING POLYURETHANE HOT MELT ADHESIVE                                              |
| 1337 | PT026787 | N-1693 | DE | 22 Oct 1998 | 98120011.6 | 10 Oct 2007 | 59838537   | ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMAL DRUG DELIVERY |
| 1338 | PT026787 | N-1693 | GB | 22 Oct 1998 | 98120011.6 | 10 Oct 2007 | 0913445    | ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMAL DRUG DELIVERY |
| 1339 | PT026787 | N-1693 | IT | 22 Oct 1998 | 98120011.6 | 10 Oct 2007 | 0913445    | ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMAL DRUG DELIVERY |
| 1340 | PT026787 | N-1693 | JP | 27 Oct 1998 | 10-305122  | 14 Jan 2011 | 4660830    | ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMAL DRUG DELIVERY |
| 1341 | PT026787 | N-1693 | US | 28 Oct 1997 | 08/958862  | 20 Jun 2000 | 6077527    | ENHANCER-RESISTANT PRESSURE SENSITIVE ADHESIVE COMPOSITION FOR TRANSDERMAL DRUG DELIVERY |
| 1342 | PT026789 | N-1695 | US | 21 Jan 1998 | 09/010082  | 15 Aug 2000 | 6103388    | USE OF LOW TOXICITY SOLVENTS IN WATERBORNE ADHESIVES                                     |
| 1343 | PT026790 | N-1698 | CA | 04 Feb 1999 | 2260675    | 06 Apr 2010 | 2260675    | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                            |
| 1344 | PT026790 | N-1698 | DE | 02 Feb 1999 | 99101564.5 | 26 Sep 2007 | 69937164.3 | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                            |
| 5    | PT026790 | N-1698 | ES | 02 Feb 1999 | 99101564.5 | 26 Sep 2007 | 0934990    | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                            |
| 6    | PT026790 | N-1698 | FR | 02 Feb 1999 | 99101564.5 | 26 Sep 2007 | 0934990    | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                            |
| 7    | PT026790 | N-1698 | GB | 02 Feb 1999 | 99101564.5 | 26 Sep 2007 | 0934990    | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                            |
| 8    |          |        |    |             |            |             |            |                                                                                          |

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REEL: 066369 FRAME: 0886

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|      | A        | B      | D  | E           | F          | G           | H             | M                                                                                |
|------|----------|--------|----|-------------|------------|-------------|---------------|----------------------------------------------------------------------------------|
| 1349 | PT026790 | N-1698 | JP | 03 Feb 1999 | 11-025853  | 15 Jul 2011 | 4782258       | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                    |
|      | PT026790 | N-1698 | MX | 03 Feb 1999 | 991234     | 20 May 2003 | 214341        | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                    |
| 1350 | PT026790 | N-1698 | US | 04 Feb 1998 | 09/018634  | 12 Sep 2000 | 6117945       | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                    |
| 1351 | PT026791 | N-1699 | US | 12 Nov 1998 | 09/190156  | 13 Mar 2001 | 6201099       |                                                                                  |
| 1352 | PT026794 | N-1710 | JP | 22 Jan 1999 | 11-014250  | 14 Jan 2011 | 4660699       | ADHESIVE COMPOSITION WITH SMALL PARTICLE SIZE FOR MICROELECTRONIC DEVICES        |
| 1353 | PT026794 | N-1710 | KR | 22 Jan 1999 | 99-1962    | 24 Mar 2006 | 10-0566551    | ADHESIVE COMPOSITION WITH SMALL PARTICLE SIZE FOR MICROELECTRONIC DEVICES        |
| 1354 | PT026794 | N-1710 | US | 23 Jan 1998 | 09/012354  | 08 Feb 2000 | 6022616       | ADHESIVE COMPOSITION WITH SMALL PARTICLE SIZE FOR MICROELECTRONIC DEVICES        |
| 1355 | PT026807 | N-1731 | CN | 30 Jun 1999 | 99110932.5 | 02 Nov 2005 | 99110932.5    | METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS |
| 1356 | PT026807 | N-1731 | DE | 01 Jul 1999 | 99112733.3 | 11 Oct 2006 | 69933512.4-08 | METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS |
| 1357 | PT026807 | N-1731 | FI | 01 Jul 1999 | 99112733.3 | 11 Oct 2006 | 0969064       | METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS |
| 8    | PT026807 | N-1731 | FR | 01 Jul 1999 | 99112733.3 | 11 Oct 2006 | 0969064       | METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS |
| 9    | PT026807 | N-1731 | IT | 01 Jul 1999 | 99112733.3 | 11 Oct 2006 | 0969064       | METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS |
| 10   | PT026807 | N-1731 | KR | 01 Jul 1999 | 99-26328   | 21 Sep 2005 | 10-0517454    | METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS |

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|      | A        | B      | D  | E           | F               | G           | H          | M                                                                                |
|------|----------|--------|----|-------------|-----------------|-------------|------------|----------------------------------------------------------------------------------|
|      | PT026807 | N-1731 | US | 02 Jul 1998 | 09/110080       | 02 May 2000 | 6057381    | METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS |
| 1362 | PT026807 | N-1731 | US | 22 Dec 1999 | 09/469479       | 30 Jan 2001 | 6180187    | METHOD OF MAKING AN ELECTRONIC COMPONENT USING REWORKABLE UNDERFILL ENCAPSULANTS |
| 1363 | PT026810 | N-1734 | CN | 30 Jun 1999 | 99111395.0      | 14 Apr 2004 | 99111395.0 | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
| 1364 | PT026810 | N-1734 | CN | 10 Apr 2001 | 01119283.6      | 19 Apr 2006 | 01119283.6 | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
| 1365 | PT026810 | N-1734 | DE | 01 Jul 1999 | 99112734.1      | 06 Oct 2004 | 69920813   | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
| 1366 | PT026810 | N-1734 | FR | 01 Jul 1999 | 99112734.1      | 06 Oct 2004 | 0969065    | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
| 1367 | PT026810 | N-1734 | IT | 01 Jul 1999 | 99112734.1      | 06 Oct 2004 | 0969065    | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
| 1368 | PT026810 | N-1734 | KR | 02 Jul 1999 | 99-26638        | 12 Jul 2006 | 10-0602887 | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
| 1369 | PT026810 | N-1734 | KR | 10 Apr 2001 | 10-2001-0019038 | 17 Jan 2008 | 10-0795423 | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
| 0    | PT026810 | N-1734 | NL | 01 Jul 1999 | 99112734.1      | 06 Oct 2004 | 0969065    | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
| 1    | PT026810 | N-1734 | TW | 01 Jul 1999 | 88111220        | 24 Dec 2002 | 162346     | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
| 2    | PT026810 | N-1734 | US | 02 Jul 1998 | 60/091492       |             |            | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES                          |
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| 1374 | PT026810 | N-1734 | US | 14 Apr 2000 | 09/549639      | 12 Mar 2002 | 6355750        | DIE ATTACH ADHESIVES FOR USE IN MICROELECTRONIC DEVICES          |
| 1375 | PT026811 | N-1735 | US | 02 Jul 1998 | 09/110047      | 16 May 2000 | 6063828        | Underfill Encapsulant Compositions For Use In Electronic Devices |
| 1376 | PT026812 | N-1736 | CN | 30 Jun 1999 | 99119202.8     | 03 Mar 2004 | 99119202.8     | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |
| 1377 | PT026812 | N-1736 | CN | 14 Aug 2000 | 200310124361.9 | 19 Jul 2006 | 200310124361.9 | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |
| 1378 | PT026812 | N-1736 | DE | 01 Jul 1999 | 99112725.9     | 11 Apr 2007 | 69935758.6-08  | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |
| 1379 | PT026812 | N-1736 | FR | 01 Jul 1999 | 99112725.9     | 11 Apr 2007 | 0969063        | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |
| 1380 | PT026812 | N-1736 | IT | 01 Jul 1999 | 99112725.9     | 11 Apr 2007 | 0969063        | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |
| 1381 | PT026812 | N-1736 | JP | 02 Jul 1999 | 189376/99      | 19 Apr 2002 | 3299522        | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |
| 2    | PT026812 | N-1736 | NL | 01 Jul 1999 | 99112725.9     | 11 Apr 2007 | 0969063        | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |
| 3    | PT026812 | N-1736 | TW | 01 Jul 1999 | 88111221       | 10 Sep 2002 | NI-155712      | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |
| 4    | PT026812 | N-1736 | US | 02 Jul 1998 | 60/091493      |             |                | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |
| 35   | PT026812 | N-1736 | US | 18 Jun 1999 | 09/336246      | 13 Nov 2001 | 6316566        | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES   |

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|      | PT026812            | N-1736            | US            | 28 Jun 2001            | 09/894540            | 26 Feb 2002 | 6350838       | PACKAGE ENCAPSULANT COMPOSITIONS FOR USE IN ELECTRONIC DEVICES                             |
| 1386 | PT026816            | N-1749            | EP            | 14 Jul 2000            | 00948685.3           | 11 Mar 2009 | 1301565       | REAGENTS FOR HEAT ACTIVATED POLYMER CROSSLINKING                                           |
| 1387 | <del>PT026822</del> | <del>N-1771</del> | <del>US</del> | <del>04 Nov 1998</del> | <del>09/186237</del> |             |               |                                                                                            |
| 1388 | PT026825            | N-1786            | DE            | 05 Apr 2000            | 00107108.3           | 08 Dec 2004 | 60016493.4-08 | USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS |
| 1389 | PT026825            | N-1786            | FR            | 05 Apr 2000            | 00107108.3           | 08 Dec 2004 | 1043376       | USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS |
| 1390 | PT026825            | N-1786            | GB            | 05 Apr 2000            | 00107108.3           | 08 Dec 2004 | 1043376       | USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS |
| 1391 | PT026825            | N-1786            | JP            | 07 Apr 2000            | 2000-111920          | 05 Nov 2010 | 4620213       | USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS |
| 1392 | PT026825            | N-1786            | US            | 09 Apr 1999            | 09/289451            | 14 Dec 1999 | 6001910       | USE OF ANIONIC OR CATIONIC PLASTICIZERS WITH SULFONATED POLYESTERS IN HOTMELT FORMULATIONS |
| 13   | PT026826            | N-1791            | CN            | 23 Dec 1999            | 99122973.8           | 18 Oct 2006 | 99122973.8    | MULTIPURPOSE HOT MELT ADHESIVE                                                             |
| 14   | PT026826            | N-1791            | DE            | 22 Dec 1999            | 99125904.5           | 25 Feb 2009 | 69940460.6-08 | MULTIPURPOSE HOT MELT ADHESIVE                                                             |
| 15   | PT026826            | N-1791            | GB            | 22 Dec 1999            | 99 125 904.5         | 25 Feb 2009 | 1013733       | MULTIPURPOSE HOT MELT ADHESIVE                                                             |
| 16   |                     |                   |               |                        |                      |             |               |                                                                                            |

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|      | PT026826 | N-1791 | IT | 22 Dec 1999 | 99 125 904.5 | 25 Feb 2009 | 1013733    | MULTIPURPOSE HOT MELT ADHESIVE                                            |
| 1397 | PT026826 | N-1791 | JP | 22 Dec 1999 | 11-363997    | 03 Aug 2012 | 5053474    | MULTIPURPOSE HOT MELT ADHESIVE                                            |
| 1398 | PT026826 | N-1791 | KR | 23 Dec 1999 | 99-60911     | 16 Mar 2009 | 10-0889998 | MULTIPURPOSE HOT MELT ADHESIVE                                            |
| 1399 | PT026826 | N-1791 | MX | 17 Dec 1999 | 9912107      | 22 Mar 2004 | 219488     | MULTIPURPOSE HOT MELT ADHESIVE                                            |
| 1400 | PT026826 | N-1791 | SE | 22 Dec 1999 | 99 125 904.5 | 25 Feb 2009 | 1013733    | MULTIPURPOSE HOT MELT ADHESIVE                                            |
| 1401 | PT026826 | N-1791 | TW | 21 Dec 1999 | 88122598     |             |            | MULTIPURPOSE HOT MELT ADHESIVE                                            |
| 1402 | PT026826 | N-1791 | US | 23 Dec 1998 | 09/219938    | 15 May 2001 | 6232391    | MULTIPURPOSE HOT MELT ADHESIVE                                            |
| 1403 | PT026826 | N-1791 | US | 13 Apr 2000 | 09/548545    | 21 May 2002 | 6391960    | MULTIPURPOSE HOT MELT ADHESIVE                                            |
| 1404 | PT026829 | N-1797 | CH | 23 Jun 2000 | 10154218.1   | 24 Jul 2013 | 2183986    | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE<br>FOR CIGARETTEPREPARATION |
| 5    | PT026829 | N-1797 | DE | 23 Jun 2000 | 10154218.1   | 24 Jul 2013 | 60048155.7 | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE<br>FOR CIGARETTEPREPARATION |
| 6    | PT026829 | N-1797 | DE |             |              |             |            | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE<br>FOR CIGARETTEPREPARATION |
| 7    | PT026829 | N-1797 | EP | 23 Jun 2000 | 10154218.1   | 24 Jul 2013 | 2183986    | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE<br>FOR CIGARETTEPREPARATION |
| 8    |          |        |    |             |              |             |            |                                                                           |

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|      | PT026829 | N-1797 | SE | 23 Jun 2000 | 10154218.1   | 24 Jul 2013 | 2183986    | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE FOR CIGARETTE PREPARATION                    |
| 1419 | PT026829 | N-1797 | US | 26 Apr 1999 | 09/299516    | 27 May 2003 | 6568399    | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE FOR CIGARETTE PREPARATION                    |
| 1420 | PT026830 | N-1803 | US | 09 Mar 1999 | 09/264999    | 26 Dec 2000 | 6165613    | Adhesive Paste for Semiconductors                                                          |
| 1421 | PT026831 | N-1805 | US | 13 Feb 2001 | 09/782421    | 05 Feb 2002 | 6344157    | CONDUCTIVE AND RESISTIVE MATERIALS WITH ELECTRICAL STABILITY FOR USE IN ELECTRONIC DEVICES |
| 1422 | PT026832 | N-1806 | JP | 07 Apr 2000 | 2000-111922  | 17 Dec 2010 | 4644769    | HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS COMPRISING WETNESS INDICATOR             |
| 1423 | PT026832 | N-1806 | MX | 07 Apr 2000 | 3454         | 28 Jan 2008 | 253915     | HOT MELT ADHESIVES BASED ON SULFONATED POLYESTERS COMPRISING WETNESS INDICATOR             |
| 1424 | PT026833 | N-1807 | JP | 07 Apr 2000 | 2000-111923  | 17 Dec 2010 | 4644770    | USE OF HIGH HYDROXYL COMPOUNDS FOR WATER SENSITIVE HOT MELT ADHESIVES                      |
| 1425 | PT026833 | N-1807 | US | 09 Apr 1999 | 09/289025    | 25 Jun 2002 | 6410627    | USE OF HIGH HYDROXYL COMPOUNDS FOR WATER SENSITIVE HOT MELT ADHESIVES                      |
| 1426 | PT026838 | N-1824 | CN | 16 May 2001 | 01119711.0   | 11 Jan 2006 | 01119711.0 | CURABLE ELECTRON DONOR COMPOUNDS                                                           |
| 7    | PT026838 | N-1824 | EP | 16 May 2001 | 01111274.5   |             |            | CURABLE ELECTRON DONOR COMPOUNDS                                                           |
| 8    | PT026838 | N-1824 | JP | 16 May 2001 | 2001-146658  | 14 Nov 2008 | P4216489   | CURABLE ELECTRON DONOR COMPOUNDS                                                           |
| 9    | PT026838 | N-1824 | JP | 05 Sep 2008 | 2008-228932  | 25 Nov 2011 | 4870738    | CURABLE ELECTRON DONOR COMPOUNDS                                                           |
| 10   | PT026838 | N-1824 | KR | 16 May 2001 | 2001-0026768 | 08 Jan 2008 | 10-0794633 | CURABLE ELECTRON DONOR COMPOUNDS                                                           |
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|      | PT026840 | N-1827 | JP | 07 Jun 2000 | 2001-502528 | 07 Sep 2012 | 5079957       | HOT MELT PRESSURE SENSITIVE ADHESIVE BASED ON COMPATIBILIZED BLENDS OF ELASTOMERS |
| 1432 | PT026840 | N-1827 | US | 07 Jun 1999 | 09/326856   | 19 Dec 2000 | 6162859       | HOT MELT PRESSURE SENSITIVE ADHESIVE BASED ON COMPATIBILIZED BLENDS OF ELASTOMERS |
| 1433 | PT026842 | N-1829 | CN | 07 Jul 1999 | 99110951.1  | 06 Oct 2004 | 99110951.1    | EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS                           |
| 1434 | PT026842 | N-1829 | DE | 07 Jul 1999 | 99113152.5  | 17 Sep 2003 | 69911320.2    | EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS                           |
| 1435 | PT026842 | N-1829 | GB | 07 Jul 1999 | 99113152.5  | 17 Sep 2003 | 971009        | EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS                           |
| 1436 | PT026842 | N-1829 | JP | 07 Jul 1999 | 1999-193327 | 20 Nov 2009 | 4408484       | EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS                           |
| 1437 | PT026842 | N-1829 | SG | 07 Jul 1999 | 9903317-7   | 31 Aug 2006 | 74150         | EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS                           |
| 1438 | PT026842 | N-1829 | US | 06 Jul 1999 | 09/347794   | 01 May 2001 | 6225379       | EPOXY RESIN COMPOSITION FOR BONDING SEMICONDUCTOR CHIPS                           |
| 1439 | PT026843 | N-1839 | US | 14 Oct 1999 | 09/417347   |             |               |                                                                                   |
| 1440 | PT026845 | N-1843 | DE | 31 Oct 2000 | 00123391.5  | 09 Feb 2005 | 60018015.8-08 | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                     |
| 1441 | PT026845 | N-1843 | FR | 31 Oct 2000 | 001233915   | 09 Feb 2005 | 1099742       | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                                     |

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|      | PT026845 | N-1843     | GB | 31 Oct 2000 | 001233915  | 09 Feb 2005 | 1099742 | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                     |
| 1443 | PT026845 | N-1843     | IT | 31 Oct 2000 | 001233915  | 09 Feb 2005 | 1099742 | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                     |
| 1444 | PT026845 | N-1843     | SE | 31 Oct 2000 | 001233915  | 09 Feb 2005 | 1099742 | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                     |
| 1445 | PT026845 | N-1843     | US | 12 Nov 1999 | 09/439655  | 28 Mar 2006 | 7019060 | LOW APPLICATION TEMPERATURE HOT MELT ADHESIVE                     |
| 1446 | PT026849 | N-1852     | US | 18 May 2000 | 09/573838  | 09 Oct 2001 | 6300456 | COMPOUNDS WITH ELECTRON DONOR AND ELECTRON ACCEPTOR FUNCTIONALITY |
| 1447 | PT026850 | N-1853.TDM | CH | 08 Feb 2001 | 01909120.6 | 15 Apr 2009 | 1257258 | BIOADHESIVE COMPOSITION                                           |
| 1448 | PT026850 | N-1853.TDM | DE | 08 Feb 2001 | 01909120.6 | 15 Apr 2009 | 1257258 | BIOADHESIVE COMPOSITION                                           |
| 1449 | PT026850 | N-1853.TDM | FR | 08 Feb 2001 | 01909120.6 | 15 Apr 2009 | 1257258 | BIOADHESIVE COMPOSITION                                           |
| 0    | PT026850 | N-1853.TDM | GB | 08 Feb 2001 | 01909120.6 | 15 Apr 2009 | 1257258 | BIOADHESIVE COMPOSITION                                           |
| 1    | PT026850 | N-1853.TDM | US | 11 Feb 2000 | 09/502585  | 04 Sep 2001 | 6284235 | BIOADHESIVE COMPOSITION                                           |
| 2    | PT026851 | N-1858     | US | 29 Feb 2000 | 09/515881  | 18 Nov 2003 | 6649259 | ADHESIVES FOR THERMALLY SHRINKABLE FILMS OR LABELS                |
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| 1454 | PT026852 | N-1859 | US | 02 Mar 2000 | 09/517412    | 26 Nov 2002 | 6486229       |                                                                           |
|      | PT026853 | N-1860 | JP | 05 Apr 2001 | 2001-575103  | 04 Nov 2011 | 4854161       | WATER BASED ADHESIVE COMPOSITION WITH RELEASE PROPERTIES                  |
| 1455 | PT026853 | N-1860 | US | 05 Apr 2000 | 09/543692    | 14 May 2002 | 6387475       | WATER BASED ADHESIVE COMPOSITION WITH RELEASE PROPERTIES                  |
| 1456 | PT026854 | N-1861 | CN | 16 May 2001 | 01119710.2   | 15 Dec 2004 | 01119710.2    | DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY |
| 1457 | PT026854 | N-1861 | DE | 16 May 2001 | 01111271.1   | 16 Mar 2005 | 60109356.9-08 | DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY |
| 1458 | PT026854 | N-1861 | FR | 16 May 2001 | 01111271.1   | 16 Mar 2005 | 1156068       | DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY |
| 1459 | PT026854 | N-1861 | IT | 16 May 2001 | 01111271.1   | 16 Mar 2005 | 1156068       | DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY |
| 1460 | PT026854 | N-1861 | KR | 16 May 2001 | 2001-0026769 | 20 Dec 2007 | 10-0789332    | DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY |
| 1461 | PT026854 | N-1861 | TW | 17 May 2001 | 90112030     | 01 Oct 2008 | I-301491      | DIE ATTACH ADHESIVES WITH VINYL ETHER AND CARBAMATE OR UREA FUNCTIONALITY |
| 2    | PT026859 | N-1869 | CN | 05 Jul 2001 | 01122563.7   | 16 Mar 2005 | 01122563.7    | DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYL GROUPS        |
| 3    | PT026859 | N-1869 | DE | 04 Jul 2001 | 01115670.0   | 16 Mar 2005 | 60109366.6-08 | DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYL GROUPS        |
| 4    | PT026859 | N-1869 | EP | 04 Jul 2001 | 01115670.0   | 16 Mar 2005 | 1170346       | DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYL GROUPS        |

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|      | PT026859 | N-1869 | FR | 04 Jul 2001 | 01115670.0   | 16 Mar 2005 | 1170346    | DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS               |
| 1466 | PT026859 | N-1869 | IT | 04 Jul 2001 | 01115670.0   | 16 Mar 2005 | 1170346    | DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS               |
| 1467 | PT026859 | N-1869 | JP | 04 Jul 2001 | 2001-203485  | 02 Jul 2010 | 4541599    | DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS               |
| 1468 | PT026859 | N-1869 | KR | 05 Jul 2001 | 2001-0040099 | 08 Jan 2008 | 794636     | DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS               |
| 1469 | PT026859 | N-1869 | TW | 04 Jul 2001 | 90116527     | 21 Dec 2004 | 225513     | DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS               |
| 1470 | PT026859 | N-1869 | US | 07 Jul 2000 | 09/611899    | 15 Jun 2004 | 6750301    | DIE ATTACH ADHESIVES WITH EPOXY RESIN HAVING ALLYL OR VINYLGROUPS               |
| 1471 | PT026860 | N-1870 | US | 23 Jun 2000 | 09/603155    | 28 Aug 2001 | 6280515    |                                                                                 |
| 1472 | PT026861 | N-1871 | US | 23 Jun 2000 | 09/602736    | 28 Aug 2001 | 6280514    |                                                                                 |
| 1473 | PT026862 | N-1873 | US | 21 Apr 2000 | 09/556721    | 19 Nov 2002 | 6482878    | POLYURETHANE HOTMELT ADHESIVES WITH ACRYLIC COPOLYMERS AND THERMOPLASTIC RESINS |
| 1474 | PT026863 | N-1875 | BE | 19 Jun 2000 | 00942950.7   | 18 Sep 2002 | 1121295    | GLUE FOR LABELS                                                                 |
| 5    | PT026863 | N-1875 | DE | 19 Jun 2000 | 00942950.7   | 18 Sep 2002 | 60000477.5 | GLUE FOR LABELS                                                                 |
| 6    | PT026863 | N-1875 | ES | 19 Jun 2000 | 00942950.7   | 18 Sep 2002 | 1121295    | GLUE FOR LABELS                                                                 |
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| 1478 | PT026863 | N-1875     | FR | 19 Jun 2000 | 00942950.7 | 18 Sep 2002 | 1121295 | GLUE FOR LABELS                                                               |
| 1479 | PT026863 | N-1875     | GB | 19 Jun 2000 | 00942950.7 | 18 Sep 2002 | 1121295 | GLUE FOR LABELS                                                               |
| 1480 | PT026863 | N-1875     | IT | 19 Jun 2000 | 00942950.7 | 18 Sep 2002 | 1121295 | GLUE FOR LABELS                                                               |
| 1481 | PT026863 | N-1875     | NL | 19 Jun 2000 | 00942950.7 | 18 Sep 2002 | 1121295 | GLUE FOR LABELS                                                               |
| 1482 | PT026870 | N-1892     | US | 18 Oct 2000 | 09/523378  | 25 Mar 2003 | 6537359 | CONDUCTIVE INK OR PAINT                                                       |
| 1483 | PT026873 | N-1899     | US | 25 Oct 2000 | 09/596799  | 18 Nov 2003 | 6648955 | Corrugating adhesive                                                          |
| 1484 | PT026881 | N-1912     | US | 29 Dec 2000 | 09/752260  | 10 Sep 2002 | 6448303 | HOT MELT ADHESIVES FOR DERMAL APPLICATION                                     |
| 1485 | PT026882 | N-1913.EEM | US | 09 Jan 2001 | 09/757210  | 03 Jun 2003 | 6572790 | CATHODE COATING DISPERSION                                                    |
| 16   | PT026884 | N-1917.ADH | US | 06 Feb 2001 | 09/777281  | 15 Jul 2003 | 6593407 | HOT MELT ADHESIVE COMPOSITION                                                 |
| 17   | PT026885 | N-1922.PSA | US | 16 Mar 2001 | 09/809802  | 04 Nov 2003 | 6642298 | Rubber-acrylic adhesive formulation                                           |
| 18   | PT026886 | N-1925.EEM | US | 25 Apr 2001 | 09/841980  | 24 Jun 2003 | 6583201 | CONDUCTIVE MATERIALS WITH ELECTRICAL STABILITY FOR USE IN ELECTRONICS DEVICES |
| 19   | PT026887 | N-1927.BKB | US | 27 Apr 2001 | 09/844907  | 22 Feb 2005 | 6858695 | CURABLE HOT MELT ADHESIVES FOR CASEMAKING                                     |
| 20   | PT026889 | N-1930.EEM | US | 21 Jun 2001 | 09/887450  | 10 Dec 2002 | 6492437 | SOLVENT-BASED PROCESS FOR MANUFACTURING LATENT CURING CATALYSTS               |
| 21   | PT026890 | N-1932.BDG | US | 15 Jun 2001 | 09/882115  | 02 Sep 2003 | 6613836 | REACTIVE HOT MELT ADHESIVE                                                    |

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| 1492 | PT026892 | N-1935.PSA | US | 26 Jun 2001 | 09/891985       | 12 Oct 2004 | 6803081 | RADIATION CURABLE ADHESIVE                                                              |
|      | PT026929 | N-2023.PKG | CN | 06 May 2003 | 03810316.8      |             |         | HOT MELT ADHESIVE COMPOSITION                                                           |
| 1493 | PT027174 | N-3248.EM  | TW | 16 May 2008 | 97117929        |             |         | ORGANIC ELECTRONIC DEVICES PROTECTED BY ELASTOMERIC LAMINATING ADHESIVE                 |
| 1494 | PT026382 | N-3266.CRG | CA | 02 Sep 2009 | 2737042         |             |         | Water Resistant Adhesive and Methods of Use                                             |
| 1495 | PT026382 | N-3266.CRG | US | 12 Sep 2008 | 12/209611       | 20 Mar 2012 | 8137792 | Water Resistant Adhesive and Methods of Use                                             |
| 1496 | PT026366 | N-3268.TDM | BR | 22 Oct 2009 | PI0919869.5     |             |         | Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor |
| 1497 | PT026366 | N-3268.TDM | CN | 22 Oct 2009 | 200980142499.7  |             |         | Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor |
| 1498 | PT026366 | N-3268.TDM | EP | 22 Oct 2009 | 09744012.7      |             |         | Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor |
| 1499 | PT026366 | N-3268.TDM | IN | 22 Oct 2009 | 3361/CHENP/2011 |             |         | Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor |
| 1500 | PT026366 | N-3268.TDM | JP | 22 Oct 2009 | 2011-533328     |             |         | Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor |
| 1    | PT026366 | N-3268.TDM | KR | 22 Oct 2009 | 2011-7011716    |             |         | Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor |
| 2    | PT026366 | N-3268.TDM | RU | 22 Oct 2009 | 2011120438      |             |         | Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor |
| 3    | PT026366 | N-3268.TDM | TW | 23 Oct 2009 | 98136057        |             |         | Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor |
| 4    | PT026366 | N-3268.TDM | US | 24 Apr 2012 | 13/454592       |             |         | Pharmaceutical Pellets Comprising Modified Starch and Therapeutic Applications Therefor |
| 5    | PT027200 | N-3284.ADH | EP | 09 Feb 2009 | 09707743.2      |             |         | HOT MELT ADHESIVE                                                                       |
| 6    |          |            |    |             |                 |             |         |                                                                                         |

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| 1507 | PT027208 | N-3293.BDM | US | 20 Jul 2012 | 13/553856        |             |                | BULK-HOT-MELT ADHESIVE PACKAGING                      |
| 1508 | PT027209 | N-3294.BDM | BR | 20 Mar 2009 | PI0909448.2      |             |                | Two Part Hybrid Adhesive                              |
| 1509 | PT027209 | N-3294.BDM | CA | 20 Mar 2009 | 2719758          |             |                | Two Part Hybrid Adhesive                              |
| 1510 | PT027209 | N-3294.BDM | CN | 20 Mar 2009 | 200980115869.8   |             |                | Two Part Hybrid Adhesive                              |
| 1511 | PT027209 | N-3294.BDM | EP | 20 Mar 2009 | 09726378.4       |             |                | Two Part Hybrid Adhesive                              |
| 1512 | PT027209 | N-3294.BDM | IN | 20 Mar 2009 | 3601/KOLNP/2010  |             |                | Two Part Hybrid Adhesive                              |
| 1513 | PT027209 | N-3294.BDM | JP | 20 Mar 2009 | 2011-501929      |             |                | Two Part Hybrid Adhesive                              |
| 1514 | PT027209 | N-3294.BDM | KR | 20 Mar 2009 | 10-2010-7024061  |             |                | Two Part Hybrid Adhesive                              |
| 1515 | PT027209 | N-3294.BDM | MX | 20 Mar 2009 | MX/a/2010/010677 |             |                | Two Part Hybrid Adhesive                              |
| 1516 | PT027209 | N-3294.BDM | US | 28 Mar 2008 | 12/058023        |             |                | Two Part Hybrid Adhesive                              |
| 1517 | PT027210 | N-3295.BDM | BR | 26 Mar 2009 | PI0910069.5      |             |                | HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS |
| 1518 | PT027210 | N-3295.BDM | CN | 26 Mar 2009 | 200980117875.7   |             |                | HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS |
| 1519 | PT027210 | N-3295.BDM | EP | 26 Mar 2009 | 09728873.2       |             |                | HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS |
| 1520 | PT027210 | N-3295.BDM | JP | 26 Mar 2009 | 2011-503044      |             |                | HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS |
| 1    | PT027210 | N-3295.BDM | US | 01 Apr 2008 | 12/060553        | 08 Jan 2013 | 8349123        | HIGH HEAT RESISTANT ADHESIVE AND SEALANT COMPOSITIONS |
| 2    | PT026370 | N-3309.PSA | CH | 02 Sep 2009 | 09775392.5       | 06 Jun 2012 | 2328990        | Acrylic PSA With High Impact Resistance               |
| 3    | PT026370 | N-3309.PSA | DE | 02 Sep 2009 | 09775392.5       | 06 Jun 2012 | 602009007505.5 | Acrylic PSA With High Impact Resistance               |
| 4    | PT026370 | N-3309.PSA | EP | 02 Sep 2009 | 09775392.5       | 06 Jun 2012 | 2328990        | Acrylic PSA With High Impact Resistance               |
| 5    | PT026370 | N-3309.PSA | FR | 02 Sep 2009 | 09775392.5       | 06 Jun 2012 | 2328990        | Acrylic PSA With High Impact Resistance               |
| 6    | PT026370 | N-3309.PSA | GB | 02 Sep 2009 | 09775392.5       | 06 Jun 2012 | 2328990        | Acrylic PSA With High Impact Resistance               |
| 7    | PT026370 | N-3309.PSA | IT | 02 Sep 2009 | 09775392.5       | 06 Jun 2012 | 2328990        | Acrylic PSA With High Impact Resistance               |
| 8    | PT026370 | N-3309.PSA | US | 16 Sep 2008 | 12/211500        | 24 Jan 2012 | 8101276        | Acrylic PSA With High Impact Resistance               |

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|      | PT027221 | N-3314.EM  | CN | 02 Jul 2009 | 200980125635.1 |             |         | THIXOTROPIC CONDUCTIVE COMPOSITION                                                                  |
| 1529 | PT027221 | N-3314.EM  | EP | 02 Jul 2009 | 09774486.6     |             |         | THIXOTROPIC CONDUCTIVE COMPOSITION                                                                  |
| 1530 | PT027221 | N-3314.EM  | JP | 02 Jul 2009 | 2011-516865    |             |         | THIXOTROPIC CONDUCTIVE COMPOSITION                                                                  |
| 1531 | PT027221 | N-3314.EM  | KR | 02 Jul 2009 | 2011-7001603   |             |         | THIXOTROPIC CONDUCTIVE COMPOSITION                                                                  |
| 1532 | PT027221 | N-3314.EM  | KR | 03 Apr 2013 | 2013-7008573   |             |         | THIXOTROPIC CONDUCTIVE COMPOSITION                                                                  |
| 1533 | PT027221 | N-3314.EM  | TW | 01 Jul 2009 | 98122270       |             |         | THIXOTROPIC CONDUCTIVE COMPOSITION                                                                  |
| 1534 | PT027463 | N-3319.PSA | EP | 02 Sep 2009 | 09792172.0     |             |         | ACRYLIC PRESSURE SENSITIVE ADHESIVE FORMULATION AND ARTICLES COMPRISING SAME                        |
| 1535 | PT027463 | N-3319.PSA | US | 16 Sep 2008 | 12/211481      | 14 May 2013 | 8440304 | ACRYLIC PRESSURE SENSITIVE ADHESIVE FORMULATION AND ARTICLES COMPRISING SAME                        |
| 1536 | PT027223 | N-3320.EM  | EP | 03 Jul 2008 | 08773016.4     |             |         | SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH |
| 1537 | PT027223 | N-3320.EM  | JP | 03 Jul 2008 | 2011-515055    |             |         | SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH |
| 1538 | PT027223 | N-3320.EM  | KR | 03 Jul 2008 | 2011-7001602   |             |         | SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH |
| 9    | PT027223 | N-3320.EM  | KR | 25 Jun 2013 | 2013-7016477   |             |         | SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH |
| 0    | PT027223 | N-3320.EM  | TW | 10 Dec 2008 | 97147927       |             |         | SILVER COATED FLAKY MATERIAL FILLED CONDUCTIVE CURABLE COMPOSITION AND THEAPPLICATION IN DIE ATTACH |
| 1    | PT027464 | N-3322.BDM | BR | 10 Dec 2009 | P10922194.8    |             |         | Reactive Hot Melt Adhesive                                                                          |
| 2    | PT027464 | N-3322.BDM | CN | 10 Dec 2009 | 200980149614.3 |             |         | Reactive Hot Melt Adhesive                                                                          |
| 3    | PT027464 | N-3322.BDM | EP | 10 Dec 2009 | 09832523.6     |             |         | Reactive Hot Melt Adhesive                                                                          |
| 4    | PT027464 | N-3322.BDM | US | 12 Dec 2008 | 12/333795      | 02 Oct 2012 | 8277601 | Reactive Hot Melt Adhesive                                                                          |
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|      | PT027468 | N-3327.EM  | CN | 20 Nov 2009 | 200980146563.9 |             |         | Phase Separated Curable Compositions            |
| 1546 | PT027468 | N-3327.EM  | EP | 20 Nov 2009 | 09828287.4     |             |         | Phase Separated Curable Compositions            |
| 1547 | PT027468 | N-3327.EM  | JP | 20 Nov 2009 | 2011-537650    |             |         | Phase Separated Curable Compositions            |
| 1548 | PT027468 | N-3327.EM  | KR | 20 Nov 2009 | 2011-7014190   |             |         | Phase Separated Curable Compositions            |
| 1549 | PT027468 | N-3327.EM  | TW | 20 Nov 2009 | 98139531       |             |         | Phase Separated Curable Compositions            |
| 1550 | PT027468 | N-3327.EM  | US | 13 May 2011 | 13/106967      | 23 Apr 2013 | 8426986 | Phase Separated Curable Compositions            |
| 1551 | PT027515 | N-3328.TDM | BR | 23 Apr 2010 | PI1014886-8    |             |         | Silicone Acrylic Hybrid Polymer-Based Adhesives |
| 1552 | PT027515 | N-3328.TDM | CN | 23 Apr 2010 | 201080028046.4 |             |         | Silicone Acrylic Hybrid Polymer-Based Adhesives |
| 1553 | PT027515 | N-3328.TDM | EP | 23 Apr 2010 | 10767829.4     |             |         | Silicone Acrylic Hybrid Polymer-Based Adhesives |
| 1554 | PT027515 | N-3328.TDM | JP | 23 Apr 2010 | 2012-507419    |             |         | Silicone Acrylic Hybrid Polymer-Based Adhesives |
| 5    | PT027515 | N-3328.TDM | KR | 23 Nov 2011 | 2011-7027981   |             |         | Silicone Acrylic Hybrid Polymer-Based Adhesives |
| 6    | PT027515 | N-3328.TDM | RU | 23 Nov 2011 | 2011147589     |             |         | Silicone Acrylic Hybrid Polymer-Based Adhesives |
| 7    | PT027515 | N-3328.TDM | TW | 23 Apr 2010 | 99112902       |             |         | Silicone Acrylic Hybrid Polymer-Based Adhesives |
| 1558 | PT027515 | N-3328.TDM | US | 24 Oct 2011 | 13/279721      |             |         | Silicone Acrylic Hybrid Polymer-Based Adhesives |

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|      | PT026381 | N-3329.CRG | US | 08 Jul 2011 | 13/178799       | 06 Aug 2013 | 8501326 | Wax Replacement Specialty Formulated Corrugating Adhesive                                                    |
| 1560 | PT027469 | N-3332.EM  | CN | 03 Feb 2010 | 201080006466.2  |             |         | ENCAPSULANT FOR INKJET PRINT HEAD                                                                            |
| 1561 | PT027469 | N-3332.EM  | EP | 03 Feb 2010 | 10739055.1      |             |         | ENCAPSULANT FOR INKJET PRINT HEAD                                                                            |
| 1562 | PT027469 | N-3332.EM  | JP | 03 Feb 2010 | 2011-548417     |             |         | ENCAPSULANT FOR INKJET PRINT HEAD                                                                            |
| 1563 | PT027469 | N-3332.EM  | KR | 03 Feb 2010 | 2011-7019526    |             |         | ENCAPSULANT FOR INKJET PRINT HEAD                                                                            |
| 1564 | PT027469 | N-3332.EM  | TW | 21 Jan 2010 | 99101654        |             |         | ENCAPSULANT FOR INKJET PRINT HEAD                                                                            |
| 1565 | PT027518 | N-3339.ADH | AU | 11 Jun 2010 | 201060018       |             |         | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 1566 | PT027518 | N-3339.ADH | BR | 11 Jun 2010 | PI1010733-9     |             |         | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 1567 | PT027518 | N-3339.ADH | CL | 11 Jun 2010 | 2011-3114       |             |         | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 1568 | PT027518 | N-3339.ADH | CN | 11 Jun 2010 | 201080025530.1  |             |         | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 69   | PT027518 | N-3339.ADH | EP | 11 Jun 2010 | 10786894.5      |             |         | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 70   | PT027518 | N-3339.ADH | IN | 11 Jun 2010 | 2457/MUMNP/2011 |             |         | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 71   | PT027518 | N-3339.ADH | JP | 11 Jun 2010 | 2012-515173     |             |         | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 72   | PT027518 | N-3339.ADH | KR | 11 Jun 2010 | 10-2011-7029574 |             |         | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 73   |          |            |    |             |                 |             |         |                                                                                                              |

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|      | PT027518 | N-3339.ADH | RU | 11 Jun 2010 | 2011154144       |   |   | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 1574 | PT027518 | N-3339.ADH | US | 12 Dec 2011 | 13/323090        |   |   | THERMALLY REVERSIBLE HOT MELT ADHESIVE COMPOSITION CONTAINING MULTIFUNCTIONAL DIENE AND DIENOPHILE COMPOUNDS |
| 1575 | PT027733 | N-3341.PSA | BR | 06 Sep 2012 | BR112012022560-0 |   |   | CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES                                  |
| 1576 | PT027733 | N-3341.PSA | CN | 09 Mar 2011 | 201180012600.4   |   |   | CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES                                  |
| 1577 | PT027733 | N-3341.PSA | EP | 09 Mar 2011 | 11753966.8       |   |   | CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES                                  |
| 1578 | PT027733 | N-3341.PSA | JP |             |                  |   |   | CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES                                  |
| 1579 | PT027733 | N-3341.PSA | KR | 09 Mar 2011 | 2012-7026328     |   |   | CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES                                  |
| 1580 | PT027733 | N-3341.PSA | US | 07 Sep 2012 | 13/606066        |   |   | CATIONIC UV-CROSSLINKABLE ACRYLIC POLYMERS FOR PRESSURE SENSITIVE ADHESIVES                                  |
| 1581 | PT027582 | N-3342.NWN | BR | 19 Aug 2010 | PCT/US2010/45954 |   |   | Low Temperature Hot Melt Adhesives for Disposable Articles                                                   |
| 1582 | PT027582 | N-3342.NWN | CA | 19 Aug 2010 | 2770457          |   |   | Low Temperature Hot Melt Adhesives for Disposable Articles                                                   |
| 1583 | PT027582 | N-3342.NWN | CN | 20 Feb 2012 | 201080036909.2   |   |   | Low Temperature Hot Melt Adhesives for Disposable Articles                                                   |
| 1584 | PT027582 | N-3342.NWN | EP | 19 Aug 2010 | 10810577.6       |   |   | Low Temperature Hot Melt Adhesives for Disposable Articles                                                   |
| 1585 | PT027582 | N-3342.NWN | JP | 19 Aug 2010 | 2012-525678      |   |   | Low Temperature Hot Melt Adhesives for Disposable Articles                                                   |
| 1586 | PT027582 | N-3342.NWN | KR | 19 Aug 2010 | 2012-7007172     |   |   | Low Temperature Hot Melt Adhesives for Disposable Articles                                                   |

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|      | PT027582 | N-3342.NWN | US | 20 Feb 2012 | 13/400218        |   |                     | Low Temperature Hot Melt Adhesives for Disposable Articles                       |
| 1588 | PT027577 | N-3343.PKG | BR | 30 Jul 2010 | BR112012002264.4 |   |                     | Low Application Temperature Hot Melt Adhesive                                    |
| 1589 | PT027577 | N-3343.PKG | CN | 31 Jan 2012 | 201080034001.8   |   |                     | Low Application Temperature Hot Melt Adhesive                                    |
| 1590 | PT027577 | N-3343.PKG | EP | 30 Jul 2010 | 10805084.0       |   |                     | Low Application Temperature Hot Melt Adhesive                                    |
| 1591 | PT027577 | N-3343.PKG | JP | 30 Jan 2012 | 2012-523064      |   |                     | Low Application Temperature Hot Melt Adhesive                                    |
| 1592 | PT027577 | N-3343.PKG | KR | 28 Feb 2012 | 2012-7005227     |   |                     | Low Application Temperature Hot Melt Adhesive                                    |
| 1593 | PT027577 | N-3343.PKG | US | 30 Jan 2012 | 13/361197        |   |                     | Low Application Temperature Hot Melt Adhesive                                    |
| 1594 | PT027572 | N-3346.ADH | BR | 18 Nov 2009 | PI0921170-5      |   |                     | Moisture-Curable Hot-Melt Adhesive                                               |
| 1595 | PT027572 | N-3346.ADH | CN | 18 Nov 2009 | 200980152897.7   |   |                     | Moisture-Curable Hot-Melt Adhesive                                               |
| 1596 | PT027572 | N-3346.ADH | JP | 27 Nov 2008 | 2008-302038      |   |                     | Moisture-Curable Hot-Melt Adhesive                                               |
| 1597 | PT027572 | N-3346.ADH | US | 26 May 2011 | 13/116573        |   | 04 Dec 2012 8324299 | Moisture-Curable Hot-Melt Adhesive                                               |
| 1598 | PT027599 | N-3347.PKG | US | 20 Jun 2012 | 13/528441        |   |                     | On-Guard System                                                                  |
| 1599 | PT027920 | N-3348.NWN | BR | 17 Feb 2012 | PCT/US2012/25609 |   |                     | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1600 | PT027920 | N-3348.NWN | CA | 17 Feb 2012 | PCT/US2012/25609 |   |                     | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1601 | PT027920 | N-3348.NWN | CN | 17 Feb 2012 | PCT/US2012/25609 |   |                     | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1602 | PT027920 | N-3348.NWN | EP | 17 Feb 2012 | 12747804.8       |   |                     | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1603 | PT027920 | N-3348.NWN | IN | 17 Feb 2012 | PCT/US2012/25609 |   |                     | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1604 | PT027920 | N-3348.NWN | JP | 17 Feb 2012 | PCT/US2012/25609 |   |                     | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1605 | PT027920 | N-3348.NWN | KR | 17 Feb 2012 | PCT/US2012/25609 |   |                     | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1606 | PT027920 | N-3348.NWN | MX | 17 Feb 2012 | PCT/US2012/25609 |   |                     | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1607 | PT027920 | N-3348.NWN |    |             |                  |   |                     | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |

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| 1608 | PT027920 | N-3348.NWN | RU | 17 Feb 2012 | PCT/US2012/25609 |   |   | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1609 | PT027920 | N-3348.NWN | US | 14 Mar 2013 | 13/833811        |   |   | Low Temperature, High Creep Resistant Hot Melt Adhesives for Disposable Articles |
| 1610 | PT027667 | N-3349.BDG | US | 01 Dec 2010 | 12/957842        |   |   | Moisture Curable Adhesives                                                       |
| 1611 | PT027684 | N-3350.BKB | CN | 20 Dec 2010 | 201080062237.2   |   |   | Moisture Cure Hot Melt Adhesives                                                 |
| 1612 | PT027684 | N-3350.BKB | EP | 20 Dec 2010 | 10843509.0       |   |   | Moisture Cure Hot Melt Adhesives                                                 |
| 1613 | PT027684 | N-3350.BKB | US | 22 Jun 2012 | 13/530565        |   |   | Moisture Cure Hot Melt Adhesives                                                 |
| 1614 | PT027777 | N-3352.ADH | BR | 15 Apr 2011 | BR112012027110-5 |   |   | Silicone-Acrylic Copolymer                                                       |
| 1615 | PT027777 | N-3352.ADH | CN | 15 Apr 2011 | 201180030690.X   |   |   | Silicone-Acrylic Copolymer                                                       |
| 1616 | PT027777 | N-3352.ADH | EP | 15 Apr 2011 | 11772467.4       |   |   | Silicone-Acrylic Copolymer                                                       |
| 1617 | PT027777 | N-3352.ADH | IN | 15 Apr 2011 | PCT/US2011/32609 |   |   | Silicone-Acrylic Copolymer                                                       |
| 1618 | PT027777 | N-3352.ADH | JP | 15 Apr 2011 | PCT/US2011/32609 |   |   | Silicone-Acrylic Copolymer                                                       |
| 1619 | PT027777 | N-3352.ADH | KR | 15 Apr 2011 | PCT/US2011/32609 |   |   | Silicone-Acrylic Copolymer                                                       |
| 1620 | PT027777 | N-3352.ADH | RU | 15 Apr 2011 | 2012149840       |   |   | Silicone-Acrylic Copolymer                                                       |
| 1621 | PT027777 | N-3352.ADH | US | 14 Sep 2012 | 13/617968        |   |   | Silicone-Acrylic Copolymer                                                       |
| 1622 | PT027812 | N-3354.EM  | CN | 28 Jul 2011 | 201180039855.X   |   |   | Radiation Curable Temporary Adhesive for Use in High Temperature Applications    |
| 1623 | PT027812 | N-3354.EM  | EP | 28 Jul 2011 | 11818534.7       |   |   | Radiation Curable Temporary Adhesive for Use in High Temperature Applications    |
| 24   | PT027812 | N-3354.EM  | JP | 28 Jul 2011 | 2013-524861      |   |   | Radiation Curable Temporary Adhesive for Use in High Temperature Applications    |
| 25   | PT027812 | N-3354.EM  | KR | 15 Feb 2013 | 10-2013-7003816  |   |   | Radiation Curable Temporary Adhesive for Use in High Temperature Applications    |
| 26   | PT027812 | N-3354.EM  | TW | 16 Aug 2011 | 100129276        |   |   | Radiation Curable Temporary Adhesive for Use in High Temperature Applications    |
| 27   | PT027812 | N-3354.EM  | US | 14 Sep 2012 | 13/618203        |   |   | Radiation Curable Temporary Adhesive for Use in High Temperature Applications    |
| 28   | PT027817 | N-3355.CRG | CA | 29 Jul 2011 | 2747524          |   |   | Corrugating Adhesive and Use Thereof                                             |
| 29   | PT027817 | N-3355.CRG | US | 26 Jul 2011 | 13/190825        |   |   | Corrugating Adhesive and Use Thereof                                             |

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|      | PT027818 | N-3356.NWN | BR | 24 Aug 2011 | PCT/US11/48933   |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 1630 | PT027818 | N-3356.NWN | CA | 24 Aug 2011 | 2807966          |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 1631 | PT027818 | N-3356.NWN | CN | 24 Aug 2011 | 201180041300.9   |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 1632 | PT027818 | N-3356.NWN | EP | 24 Aug 2011 | 11820578.0       |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 1633 | PT027818 | N-3356.NWN | IN | 24 Aug 2011 | PCT/US11/48933   |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 1634 | PT027818 | N-3356.NWN | JP | 24 Aug 2011 | 2013-526124      |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 1635 | PT027818 | N-3356.NWN | KR | 24 Aug 2011 | PCT/US11/48933   |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 1636 | PT027818 | N-3356.NWN | MX | 24 Aug 2011 | MX/a/2013/002214 |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 1637 | PT027818 | N-3356.NWN | RU | 24 Aug 2011 | 20131113169      |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 1638 | PT027818 | N-3356.NWN | US | 20 Feb 2013 | 13/771439        |   |   | Low Application Temperature Amorphous Poly-a-olefin Adhesive                          |
| 39   | PT027833 | N-3357.CRG | BR | 09 Sep 2011 |                  |   |   | Improved Adhesive Having Insulative Properties                                        |
| 40   | PT027833 | N-3357.CRG | CN | 08 Mar 2013 | 201180043368.0   |   |   | Improved Adhesive Having Insulative Properties                                        |
| 41   | PT027833 | N-3357.CRG | EP | 09 Sep 2011 | 11824167.8       |   |   | Improved Adhesive Having Insulative Properties                                        |
| 42   | PT027833 | N-3357.CRG | JP | 09 Sep 2011 | 2013-528321      |   |   | Improved Adhesive Having Insulative Properties                                        |
| 43   | PT027833 | N-3357.CRG | KR | 09 Sep 2011 | 2013-7009093     |   |   | Improved Adhesive Having Insulative Properties                                        |
| 44   | PT027833 | N-3357.CRG | MX | 09 Sep 2011 | MX/a/2013/002701 |   |   | Improved Adhesive Having Insulative Properties                                        |
| 45   | PT027833 | N-3357.CRG | US | 25 Feb 2013 | 13/775348        |   |   | Improved Adhesive Having Insulative Properties                                        |
| 46   | PT027853 | N-3358.PKG | BR |             |                  |   |   | Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation |
| 47   | PT027853 | N-3358.PKG | CN |             |                  |   |   | Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation |
| 48   |          |            |    |             |                  |   |   |                                                                                       |

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| 1649 | PT027853 | N-3358.PKG | EP | 21 Nov 2011 | 11842029.8        |   |   | Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation |
| 1650 | PT027853 | N-3358.PKG | JP |             |                   |   |   | Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation |
| 1651 | PT027853 | N-3358.PKG | KR |             |                   |   |   | Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation |
| 1652 | PT027853 | N-3358.PKG | RU |             |                   |   |   | Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation |
| 1653 | PT027853 | N-3358.PKG | US | 05 Mar 2013 | 13/785296         |   |   | Method to Improve Wax Crystal Size and Crystallinity in Hot Melt Adhesive Formulation |
| 1654 | PT027916 | N-3360.EM  | CN |             |                   |   |   | Self-Aligned Graphene Polymer Nanocomposites                                          |
| 1655 | PT027916 | N-3360.EM  | EP |             |                   |   |   | Self-Aligned Graphene Polymer Nanocomposites                                          |
| 1656 | PT027916 | N-3360.EM  | JP |             |                   |   |   | Self-Aligned Graphene Polymer Nanocomposites                                          |
| 1657 | PT027916 | N-3360.EM  | KR |             |                   |   |   | Self-Aligned Graphene Polymer Nanocomposites                                          |
| 1658 | PT027916 | N-3360.EM  | TW | 24 Feb 2012 | 101106344         |   |   | Self-Aligned Graphene Polymer Nanocomposites                                          |
| 59   | PT027916 | N-3360.EM  | US | 14 Mar 2013 | 13/803282         |   |   | Self-Aligned Graphene Polymer Nanocomposites                                          |
| 60   | PT027918 | N-3361.PKG | WO | 04 Apr 2012 | PCT/US2012/032063 |   |   | Hot Melt Adhesives For Multilayer Structure Enclosures                                |
| 61   | PT027921 | N-3363.NWN | BR |             |                   |   |   | Stretch Film Lamination Adhesive                                                      |
| 62   | PT027921 | N-3363.NWN | CA |             |                   |   |   | Stretch Film Lamination Adhesive                                                      |
| 63   | PT027921 | N-3363.NWN | CN |             |                   |   |   | Stretch Film Lamination Adhesive                                                      |

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|      | PT027921 | N-3363.NWN            | EP |             |                   |   |   | Stretch Film Lamination Adhesive                                                           |
| 1664 | PT027921 | N-3363.NWN            | IN |             |                   |   |   | Stretch Film Lamination Adhesive                                                           |
| 1665 | PT027921 | N-3363.NWN            | JP |             |                   |   |   | Stretch Film Lamination Adhesive                                                           |
| 1666 | PT027921 | N-3363.NWN            | KR |             |                   |   |   | Stretch Film Lamination Adhesive                                                           |
| 1667 | PT027921 | N-3363.NWN            | MX |             |                   |   |   | Stretch Film Lamination Adhesive                                                           |
| 1668 | PT027921 | N-3363.NWN            | RU |             |                   |   |   | Stretch Film Lamination Adhesive                                                           |
| 1669 | PT027921 | N-3363.NWN            | US | 15 Mar 2013 | 13/832917         |   |   | Stretch Film Lamination Adhesive                                                           |
| 1670 | PT031069 | N-3364.EM             | TW | 06 Jun 2013 | 102120189         |   |   | Vinyl Carbosiloxane Resins                                                                 |
| 1671 | PT031069 | N-3364.EM             | WO | 06 Jun 2012 | PCT/CN2012/076509 |   |   | Vinyl Carbosiloxane Resins                                                                 |
| 1672 | PT028001 | N-3365.ADH            | TW | 27 Aug 2012 | 101131052         |   |   | Lenticular Print Three Dimensional Image Display Device and Method of Fabricating the Same |
| 173  | PT028001 | N-3365.ADH            | WO | 27 Jul 2012 | PCT/US2012/48541  |   |   | Lenticular Print Three Dimensional Image Display Device and Method of Fabricating the Same |
| 174  | PT028002 | N-3366.EM             | US | 14 Sep 2012 | 13/618392         |   |   | Curable Oxetane Ester Compositions                                                         |
| 175  | PT028016 | N-3367.ADH            | TW | 27 Aug 2012 | 101131051         |   |   | Lenticular Print Three Dimensional Image Display and Device of Fabricating the Same        |
| 176  | PT028016 | N-3367.ADH            | WO | 27 Jul 2012 | PCT/US2012/48595  |   |   | Lenticular Print Three Dimensional Image Display and Device of Fabricating the Same        |
| 177  | PT019333 | N-3368.EM (ID-11-076) | TW | 26 Mar 2012 | 101110427         |   |   | Electroless Plating of Silver onto Graphite                                                |
| 178  | PT031207 | N-3370.ADH            | WO | 23 Jan 2013 | PCT/US2013/22714  |   |   | UV Curable Metallic Decorative Compositions                                                |

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| 1680 | PT027276 | N-7991      | US | 07 Jun 1995 | 08/480982  | 01 Oct 1996 | 5561204 | SPHERICAL CURING AGENT FOR EPOXY-RESIN, CURING AGENT MASTERBATCH FOR EPOXY RESIN AND THEIR PREPARATION |
| 1681 | PT027276 | N-7991      | US | 07 Jun 1995 | 08/480983  | 22 Oct 1996 | 5567792 | SPHERICAL CURING AGENT FOR EPOXY RESIN, CURING AGENT MASTERBATCH FOR EPOXY RESIN AND THEIR PREPARATION |
| 1682 | PT027276 | N-7991      | US | 07 Jun 1995 | 08/472617  | 10 Sep 1996 | 5554714 | SPHERICAL CURING AGENT FOR EPOXY-RESIN, CURING AGENT MASTERBATCH FOR EPOXY RESIN AND THEIR PREPARATION |
| 1683 | PT027276 | N-7991      | US | 07 Jun 1995 | 08/472616  | 07 Jan 1997 | 5591814 | SPHERICAL CURING AGENT FOR EPOXY-RESIN, CURING AGENT MASTERBATCH FOR EPOXY RESIN AND THEIR PREPARATION |
| 1684 | PT027276 | N-7991      | US | 07 Jun 1995 | 08/478067  | 20 Aug 1996 | 5548058 | SPHERICAL CURING AGENT FOR EPOXY-RESIN, CURING AGENT MASTERBATCH FOR EPOXY RESIN AND THEIR PREPARATION |
| 1685 | PT027282 | N-8324      | EP | 14 Jun 1994 | 94921329.2 | 04 Sep 2002 | 0707524 | SOLDERABLE COMPOSITION EXHIBITING ELECTRICAL ANISOTROPY                                                |
| 1686 | PT027298 | N-AAA1230-1 | US | 16 Oct 2006 | 11/581759  | 12 Jan 2010 | 7645637 | Methods for Attaching Tin Semiconductor Die                                                            |
| 1687 | PT027363 | N-CBODA-2   | US | 23 Mar 1994 | 08/216799  | 28 Feb 1995 | 5392592 | HOT MELT PRESSURE SENSITIVE ADHESIVE PACKAGING PREFORM AND METHOD                                      |
| 1688 | PT027434 | N-JM28397   | US | 22 Dec 1995 | 08/577256  | 05 Jan 1999 | 5855821 | MATERIALS FOR SEMICONDUCTOR DEVICE ASSEMBLIES                                                          |
| 39   | PT027436 | N-JM28716   | US | 10 Jun 1996 | 08/664200  | 21 Jul 1998 | 5783621 | METHOD OF DECREASING BLEED FROM ORGANIC-BASED FORMULATIONS AND ANTI-BLEED COMPOSITIONS                 |
| 30   | PT027437 | N-JM29822   | US | 06 Jun 1997 | 08/868508  | 28 Apr 1998 | 5744533 |                                                                                                        |
| 91   | PT027438 | N-JM29849   | US | 11 Feb 1997 | 08/798864  | 12 Jan 1999 | 5859105 | ORGANOSILICON-CONTAINING COMPOSITIONS CAPABLE OF RAPID CURING AT LOW TEMPERATURE                       |
| 92   | PT027439 | N-JM30414   | US | 11 Feb 1997 | 08/798863  | 22 Dec 1998 | 5852092 | ORGANOSILICON-CONTAINING COMPOSITIONS HAVING ENHANCED ADHESIVE PROPERTIES                              |

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|      | PT027440 | N-JM30677 | US | 19 May 1997 | 08/859792        | 15 Jun 1999 | 5912316 |                                                                                                |
| 1693 | PT027441 | N-JM31088 | US | 23 Sep 1997 | 08/935575        | 12 Jan 1999 | 5859110 | METHOD OF DECREASING BLEED FROM ORGANIC-BASED FORMULATIONS AND ANTI-BLEED COMPOSITIONS         |
| 1694 | PT027442 | N-JM31635 | US | 12 Aug 1998 | 09/133507        | 02 May 2000 | 6057402 |                                                                                                |
| 1695 | PT027443 | N-JM32175 | US | 08 Jul 1994 | 08/272354        | 02 Jul 1996 | 5532513 |                                                                                                |
| 1696 | PT027443 | N-JM32175 | US | 01 Jul 1998 | 09/108923        |             |         |                                                                                                |
| 1697 | PT019217 | PT019217  | WO | 25 Jul 2012 | PCT/US2012/48131 |             |         | High Polymer Content Hot Melt Adhesives For Disposable Articles                                |
| 1698 | PT028003 | PT019284  | US | 24 Aug 2011 | 13/216563        |             |         | Starch-Based Adhesive Compositions and Use Thereof                                             |
| 1699 | PT019562 | PT019562  | TW | 29 Apr 2013 | 102115304        |             |         | Thermally Insulative Composition And Electronic Devices Assembled Therewith                    |
| 1700 | PT019562 | PT019562  | WO | 05 Apr 2013 | PCT/US2013/35424 |             |         | Thermally Insulative Composition And Electronic Devices Assembled Therewith                    |
| 1701 | PT031248 |           | AR | 17 May 2013 | P130101711       |             |         | Thermoplastic film for packaging olefin hot melt adhesives                                     |
| 1702 | PT031327 |           | AR | 24 May 2013 | P130101811       |             |         | Process and methods for preparing flow-able pellets of olefin adhesives with low crystallinity |
| 1703 | PT031387 |           | CA |             |                  |             |         | 2 Component Fluid Metering and Mixing                                                          |
| 1704 | PT019096 |           | CN | 20 Jul 2011 | 201110203015.4   |             |         | AgBN based adhesive for capacitors                                                             |
| 1705 | PT031387 |           | CN |             |                  |             |         | 2 Component Fluid Metering and Mixing                                                          |
| 1706 |          |           |    |             |                  |             |         |                                                                                                |

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|      | PT031387 |   | DE |             |             |   |   | 2 Component Fluid Metering and Mixing                                                            |
| 1707 |          |   |    |             |             |   |   |                                                                                                  |
|      | PT031445 |   | GB | 14 Mar 2013 | GB1304624.8 |   |   | Hybrid adhesives capable of bonding low surface energy substrates                                |
| 1708 |          |   | TW | 14 Jun 2012 | 101121266   |   |   | Shape memory polymer background grinding film                                                    |
|      | PT019109 |   |    |             |             |   |   |                                                                                                  |
| 1709 |          |   |    |             |             |   |   |                                                                                                  |
|      | PT019096 |   | TW | 04 Jul 2012 | 101123990   |   |   | AgBN based adhesive for capacitors                                                               |
| 1710 |          |   | TW | 28 Sep 2012 | 101136021   |   |   | Curable Oxetane Ester Compositions                                                               |
|      | PT031535 |   |    |             |             |   |   |                                                                                                  |
| 1711 |          |   | TW | 03 Apr 2013 | 102112225   |   |   | FILM FOR FILLING THROUGH THE HOLE INTERCONNECTS AND POST PROCESSING FOR INTERCONNECTS SUBSTRATES |
| 1712 |          |   | TW |             |             |   |   | Curable Encapsulants And Use Thereof                                                             |
|      | PT031397 |   |    |             |             |   |   |                                                                                                  |
| 1713 |          |   | TW | 4/29/2013   | 102115307   |   |   | Thermoplastic film for packaging olefin hot melt adhesives                                       |
|      | PT031248 |   | TW | 16 May 2013 | 102117432   |   |   |                                                                                                  |
| 1714 |          |   |    |             |             |   |   |                                                                                                  |
|      | PT031327 |   | TW |             |             |   |   | Process and methods for preparing flow-able pellets of olefin adhesives with low crystallinity   |
| 1715 |          |   | TW | 5/24/2013   | 102118481   |   |   |                                                                                                  |
| '16  |          |   | TW | 17 Jul 2013 | 102125632   |   |   | Silver sintering die-attach paste with fluxing agent for metal adhesion                          |
|      | PT019456 |   |    |             |             |   |   | Reactive Hot Melt Adhesives                                                                      |
| 1716 |          |   | TW | 18 Jul 2013 |             |   |   |                                                                                                  |
| '17  |          |   |    |             |             |   |   |                                                                                                  |
|      | PT031365 |   | US | 14 Sep 2012 | 13/617440   |   |   | Non Reactive Hot Melt Adhesive Compositions with Wide Service Temperature Range                  |
| '18  |          |   | US | 26 Oct 2012 | 61/7718841  |   |   |                                                                                                  |
|      | PT031649 |   |    |             |             |   |   |                                                                                                  |
| 1719 |          |   | US | 02 Nov 2012 | 61/7721756  |   |   | Hot Melt for overmolding applications II                                                         |
|      | PT031411 |   |    |             |             |   |   |                                                                                                  |
| 720  |          |   |    |             |             |   |   |                                                                                                  |
| 721  | PT031394 |   | US | 16 Nov 2012 | 61/772375   |   |   | A Gap Filling Waterborne Adhesive Formulation                                                    |
| 722  | PT031391 |   | US | 18 Dec 2012 | 61/7738644  |   |   | Reactive Hot Melt Adhesives                                                                      |
| 723  | PT031391 |   | US | 18 Dec 2012 | 61/7738586  |   |   | Reactive Hot Melt Adhesives                                                                      |

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| 1724 | PT031323 | US | 10 Jan 2013 | 13/738348 |   |   |   | Preparation of Polymers Terminated with Alkoxysilane Groups                                                              |
| 1725 | PT031771 | US | 28 Jan 2013 | 61/757353 |   |   |   |                                                                                                                          |
| 1726 | PT031367 | US | 21 Feb 2013 | 61/767447 |   |   |   | Hot Melt adhesives based on Polypropylene (co) polymers and use thereof                                                  |
| 1727 | PT031519 | US | 12 Mar 2013 | 13/795403 |   |   |   | Use of APAO Polymers for End of Line Packaging applications                                                              |
| 1728 | PT031778 | US | 12 Mar 2013 | 13/795228 |   |   |   | Hot Melt adhesive Compositions Based on Ethylene Vinyl Acetate Copolymer                                                 |
| 1729 | PT031248 | US | 13 Mar 2013 | 13/800445 |   |   |   | Thermoplastic film for packaging olefin hot melt adhesives                                                               |
| 1730 | PT019456 | US | 14 Mar 2013 | 13/827117 |   |   |   | Silver sintering die-attach paste with fluxing agent for metal adhesion                                                  |
| 1731 | PT031327 | US | 14 Mar 2013 | 13/803814 |   |   |   | Process and methods for preparing flow-able pellets of olefin adhesives with low crystallinity                           |
| 1732 | PT031394 | US | 14 Mar 2013 | 13/804230 |   |   |   | A Gap Filling Waterborne Adhesive Formulation                                                                            |
| 733  | PT031411 | US | 14 Mar 2013 | 13/804811 |   |   |   | Hot Melt for overmolding applications II                                                                                 |
| 734  | PT031606 | US | 14 Mar 2013 | 13/826451 |   |   |   | A heat activated waterborne adhesive formulation containing microspheres to enable fiber reduction in packaging material |
| 735  | PT019496 | US | 15 Mar 2013 | 13/838164 |   |   |   | Prepreg Curing Process For Preparing Composites Having Superior Surface Finish and High Fiber Consolidation              |
| 736  | PT031231 | US | 15 Mar 2013 | 13/839138 |   |   |   | Reactive Hot Melt Adhesives                                                                                              |
| 737  | PT031387 | US | 15 Mar 2013 | 13/840063 |   |   |   | 2 Component Fluid Metering and Mixing                                                                                    |
| 738  | PT031473 | US | 15 Mar 2013 | 13/833425 |   |   |   | Prepreg Curing Process For Preparing Composites Having Superior Surface Finish and High Fiber Consolidation              |

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|      | PT031555 |   | US | 15 Mar 2013 | 13/839785 |   |   | Anaerobic Curable Compositions                                                                   |
| 1739 | PT031612 |   | US | 15 Mar 2013 | 13/840171 |   |   | Thermosetting Resin Compositions With Low Coefficient of Thermal Expansion                       |
| 1740 | PT031617 |   | US | 15 Mar 2013 | 13/840248 |   |   | Oxetaine-Containing Compounds and Compositions Thereof                                           |
| 1741 | PT031591 |   | US | 15 Mar 2013 | 13/770295 |   |   | Reactive Hot Melt Adhesives                                                                      |
| 1742 | PT031516 |   | US | 16 Mar 2013 | 13/844890 |   |   | Electronic Devices Assembled With Heat Absorbing and/or Thermally Insulating Composition         |
| 1743 | PT031487 |   | US | 18 Mar 2013 | 13/845088 |   |   | Methods and Apparatus For Controlled Single Electron Transfer Living Radical Polymerization      |
| 1744 | PT031661 |   | US | 22 Mar 2013 | 61/804332 |   |   |                                                                                                  |
| 1745 | PT031661 |   | US | 22 Mar 2013 | 61/804232 |   |   |                                                                                                  |
| 1746 | PT031252 |   | US | 29 Mar 2013 | 13/827698 |   |   | FILM FOR FILLING THROUGH THE HOLE INTERCONNECTS AND POST PROCESSING FOR INTERCONNECTS SUBSTRATES |
| 1747 | PT031632 |   | US | 08 Apr 2013 | 61/809633 |   |   | Dispense Tip Cleaning Apparatus                                                                  |
| 1748 | PT031924 |   | US | 10 May 2013 | 61/822037 |   |   | Functional Polyisobutylene-Containing Oligomers and Polymers                                     |
| 49   | PT031787 |   | US | 21 May 2013 | 61/825766 |   |   | Flexible Cyanoacrylate Compositions                                                              |
| 50   | PT031944 |   | US | 23 May 2013 | 61/826573 |   |   | Tri-layer Adhesive for the Encapsulation of Electronic Devices                                   |
| 51   | PT031959 |   | US | 07 Jun 2013 | 61/832357 |   |   | Diene/Dienophile Couples and Thermosetting Resin Compositions Having Reworkability               |
| 52   | PT031949 |   | US | 21 Jun 2013 | 61/832769 |   |   | Polyolefin Pressure Sensitive Hot Melt Adhesive                                                  |
| 53   |          |   |    |             |           |   |   |                                                                                                  |

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